

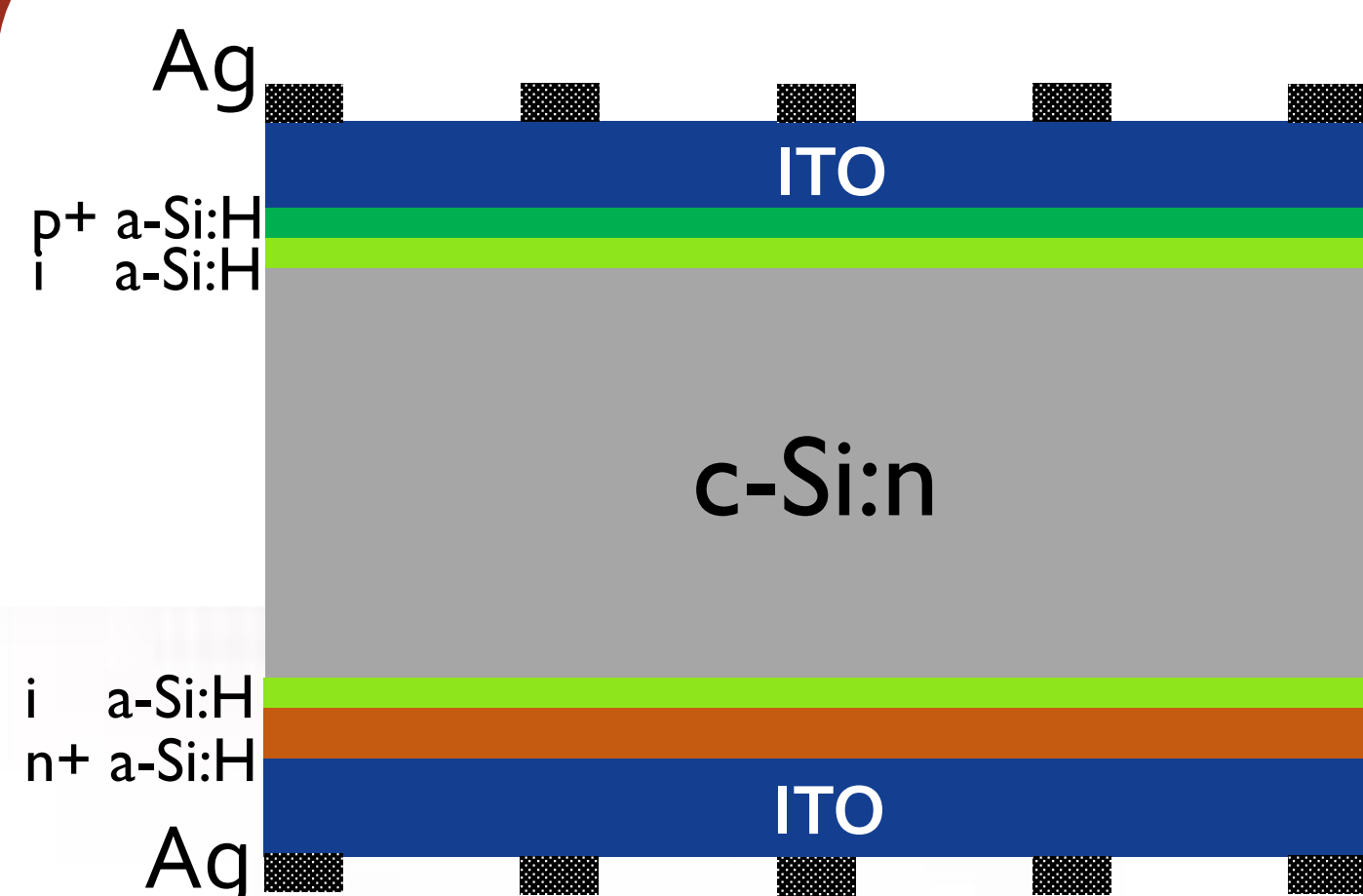
Low temperature deposition of In-free TCO using Spatial ALD for application to HET cells

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Motivation



Schematic view of an amorphous silicon/crystalline silicon heterojunction (HET) cell

Amorphous/crystalline silicon heterojunction (HET) technology allows high energy conversion efficiency (> 22 % at INES [1]) thanks to excellent passivation quality of a-Si:H/c-Si interface.

Indium Tin Oxide (ITO)

- Containing a rare element, Indium
- ITO deposition method: magnetron sputtering
→ damage to the a-Si:H/c-Si interface [2].

Replaced by

ZnO based TCOs

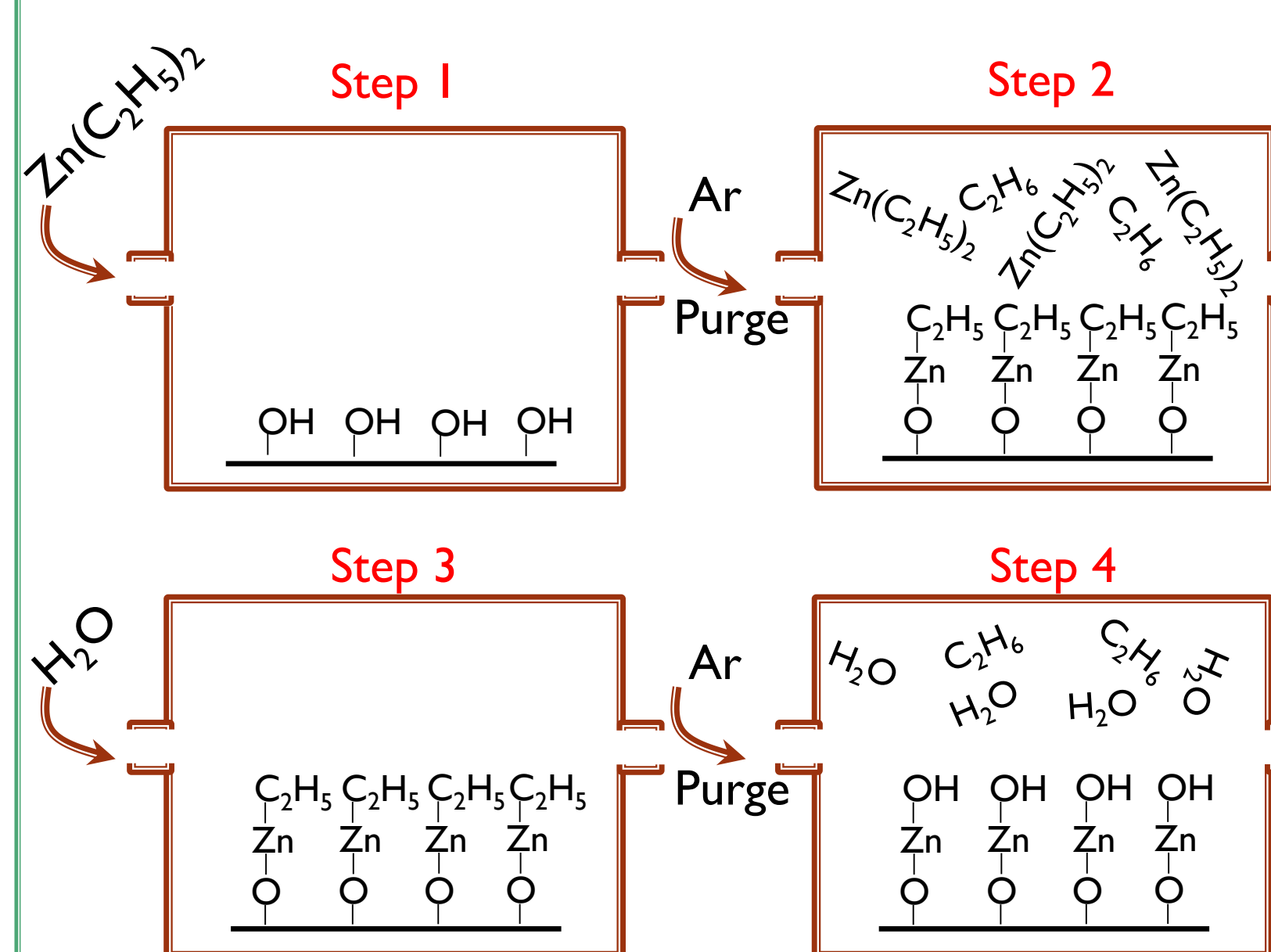
- Low-cost Transparent Conductive Oxides (TCOs)
- Low-damage deposition technique: Spatial Atomic Layer Deposition (SALD)

Objectives: Deposit Indium-free TCOs by fast, low temperature, scalable method (SALD)

Spatial Atomic Layer Deposition

Conventional ALD

Precursors separated in time



(Schematic of ALD process to grow a monolayer of ZnO, DEZ: Diethyl Zinc)

→ Repeating this cycle several times to reach the desired thickness.

High control of thickness, unique conformality, low temperature

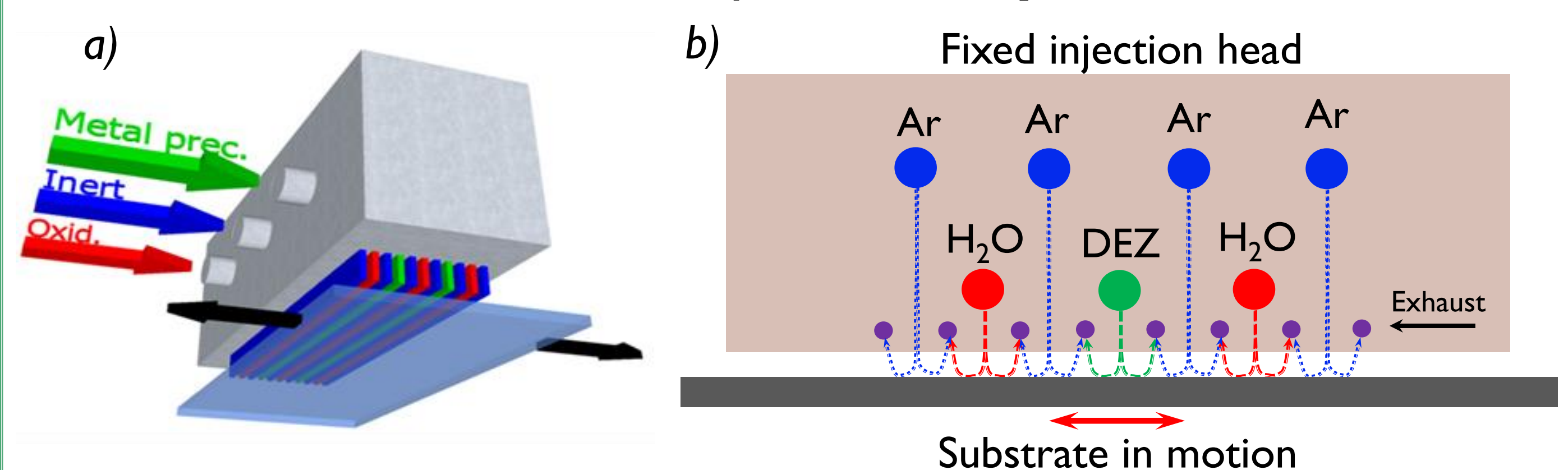
But very slow, not easy to scale

A cycle consists of:

- Step 1:** Precursor injection into reactor. A monolayer formed on surface by chemisorption
→ self-terminating process
- Step 2:** Purge (remove excess precursor)
- Step 3:** Injection of second precursor.
→ Reaction with monolayer of first precursor
- Step 4:** Purge

Spatial ALD

Precursors separated in space



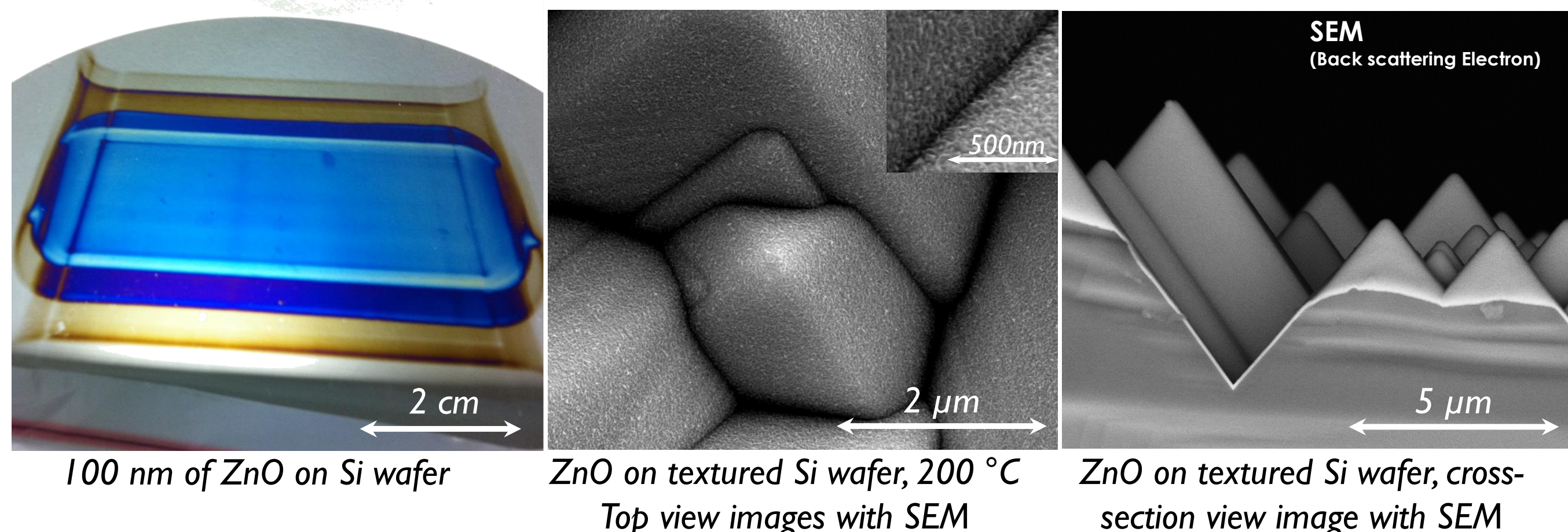
- Precursors are constantly injected in different locations, as shown in a), [3]
- Substrate moves through different gas flows, as shown in b).
- Small gap (50µm – 200µm) between injector and substrate, as well as the inert gas channels, prevent different precursors from mixing.
- Substrate will be exposed sequentially to oxidant, inert gas, metal precursor, then inert gas again and so on. This allows reproducing the cycles in conventional ALD.

Same advantages as conventional ALD

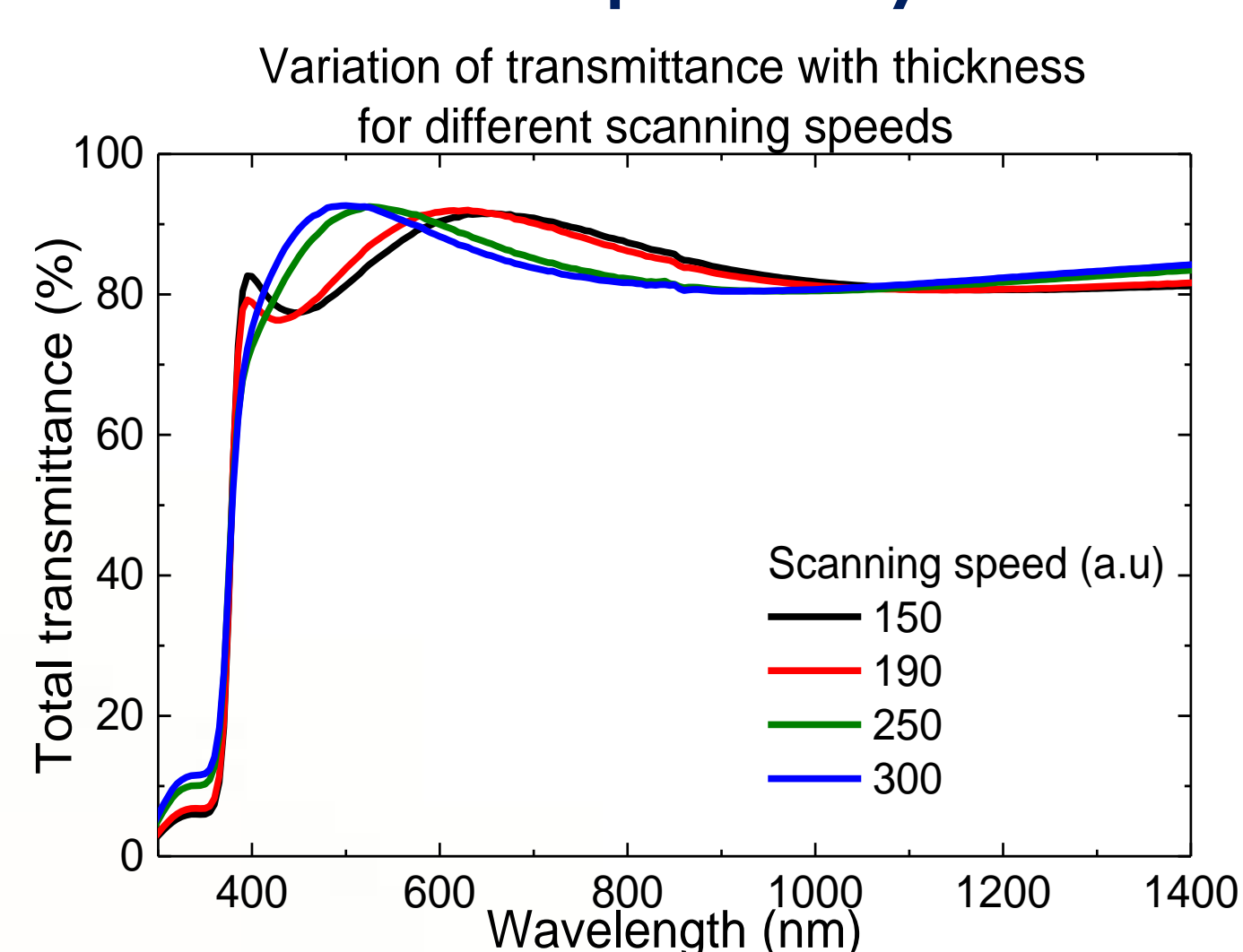
Faster, easier and cheaper to scale (atmospheric processing)

Results & discussion

High uniformity, conformity

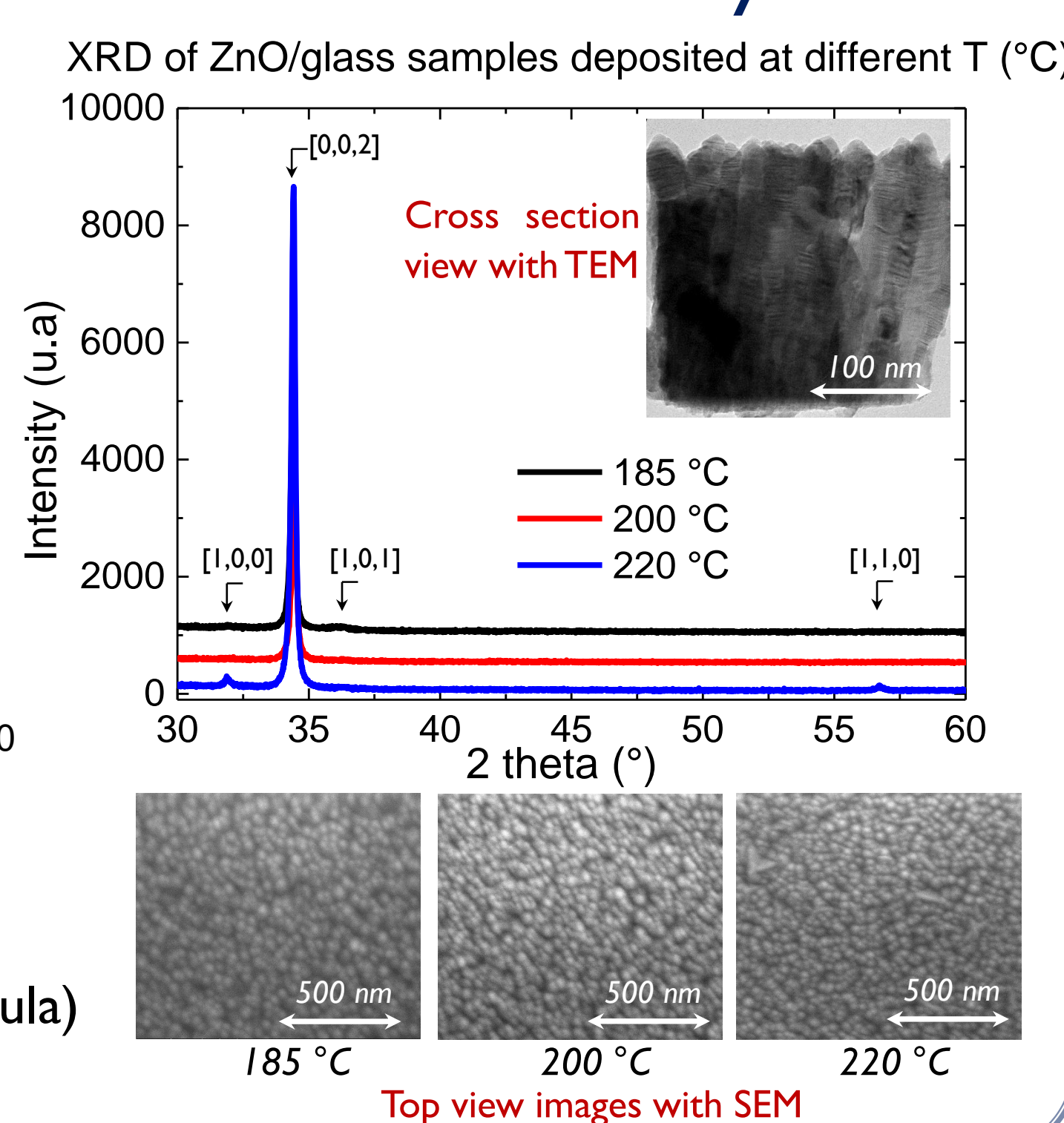


Transparency

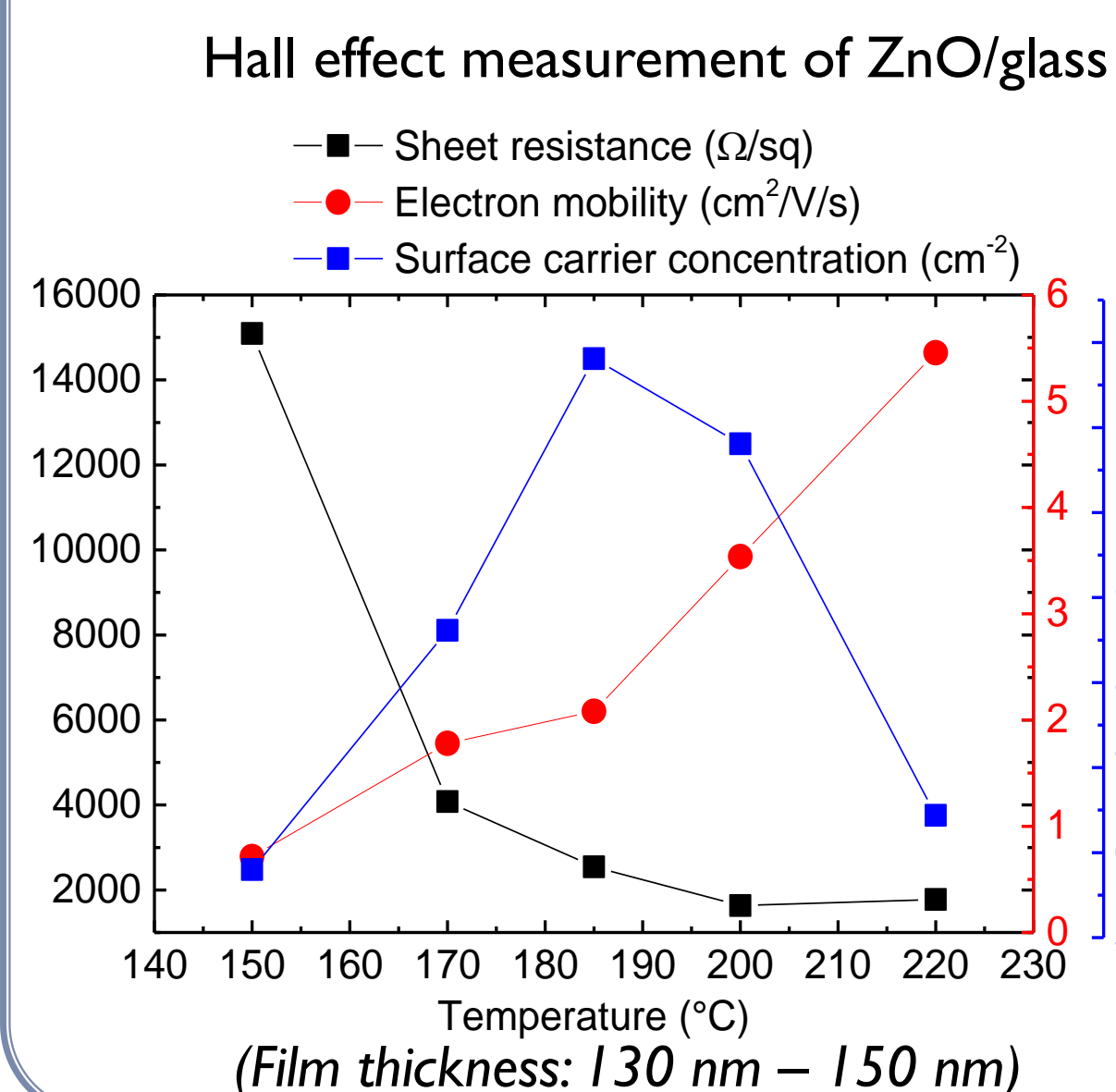


- High transmission (85% - 90%) achieved
- Slower scanning speed → thicker film
- Eg = 3,28 eV (calculated with Tauc formula)

Cristallinity



Electrical characterization



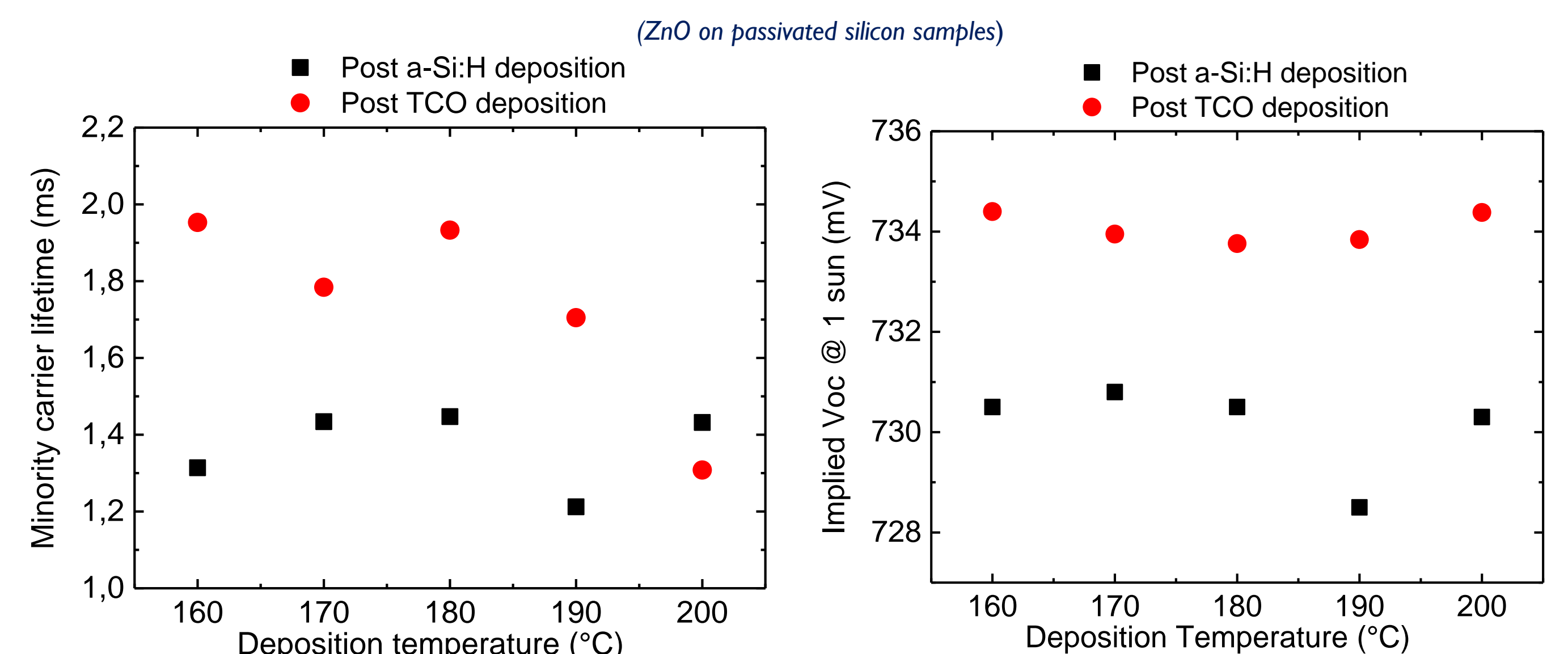
Intrinsic ZnO film deposited by SALD exhibits low resistivity (~2.5E-2 Ωcm at deposition temperature of 200 °C). However, TCOs application requires a better conductivity.

Aluminium doped Zinc Oxide (AZO)
T = 200 °C, film thickness: 200 nm

Material	Sheet Resistance (Ω/□)	Electron mobility (cm²V⁻¹s⁻¹)	Carrier concentration (cm⁻³)
ZnO	1634	3,54	5,4E+19
AZO	472	1,49	4,5E+20

Result from first AZO depositions
(Study in progress)

Passivation measurements



ZnO deposition by SALD keeps a high passivation level

Conclusions

- SALD is a fast and scalable technique which can provide high uniformity, conformity of thin film over large areas at low temperature and under atmospheric pressure.
- High transparency and low resistivity ZnO film has been obtained by SALD.
- SALD is a promising technique for TCOs deposition because it allows keeping high passivation quality in HET solar cell.

Perspectives: Study on Al-doped ZnO to improve film conductivity.

References

- [1] P. Carroy et al, *Proceedings of 31st EU-PVSEC*, Hamburg, 359, 2015
- [2] D. Zhang et al, *Energy Procedia* 8, 207–213, 2011
- [3] D. Muñoz-Rojas and J. Driscoll, *Mater Horiz.*, VI, p314, 2014